# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

| HP Pavilion dm4 Entertainment PC |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Main battery, RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers
Components, parts and materials containing radioactive substances
No
0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Cross screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 Nipper</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 P1 screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take off the battery package from system bottom side.
2. Loose DIMM/HDD door screws and take off DIMM/HDD door.
3. Loose HDD module screws and take off HDD module from system.
4. Loose ODD bracket screw and take off ODD module.
5. Loose WLAN/M-SATA screws and take off WLAN/M-SATA module from system.
6. Loose l-case to u-case screws and KB module screw, and then, take off KB module.
7. Loose u-case to l-case screws and take off u-case sub-assembly.
8. Loose MB screws and take off DC-IN cable from MB.
9. Loose hinge screws and take off hinge-up assembly.
10. Loose bezel screw and take off bezel sub-assembly.
11. Loose screws from hinge and take off LCD hinge.
12. Loose screws from LCD module and take off LCD module from panel cover.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Get Component Sequence:
1. Take off Battery Pack
2. Loose the HDD/DIMM door screws first, And then, loose the screws from HDD bracket and take off HDD module.

1. Battery pack
2. HDD Module
3. Get Screw
Disassemble Process-2

Get Component Sequence:
1. Take off the rubber and loose screws from l-case to u-case as figure 2-1.
2. Loose the screws and take off WLAN/M-SATA module.
3. Loose the screw and take off ODD module.

1. WLAN Module
2. M-SATA
3. ODD Module

A  Rubber feet
B

2-2  Get Screw
Disassemble Process-3

Get Component Sequence:
1. Loose the u-case hooks from keyboard.
2. Loose the screws from l-case near ODD module and loose the kb screw.
3. Take off the keyboard module as figure 3-3
Disassemble Process-4

Get Component Sequence:
1. Loose the five screws from u-case assembly
2. Take off the FFC cable from connector (power/touchpad/FPR/audio FFC)
3. Take off the u-case sub-assembly
4. Loose the two screws from MB.

- U-case sub-assembly
- Get FFC Cable
- Main board
- Get Screw
Get Component Sequence:
1. Take off DC-IN cable from MB and take off MB from l-case.
2. Loose two screws from DC-IN BKT and take off DC-IN cable.
3. Loose the three screws from l-case and take Off hinge-up assembly

Hinge-up assembly

Get Screw
Get Component Sequence
1. Loose two screw from bezel and take off bezel from antenna cover.
2. Take off hinge caps from antenna cover.
3. Loose four screws from hinge R/L and take off.
4. Loose four screws from LCM panel and take off.

Get Screw

Bezel
Hinge caps
LCD Hinges
LCM panel